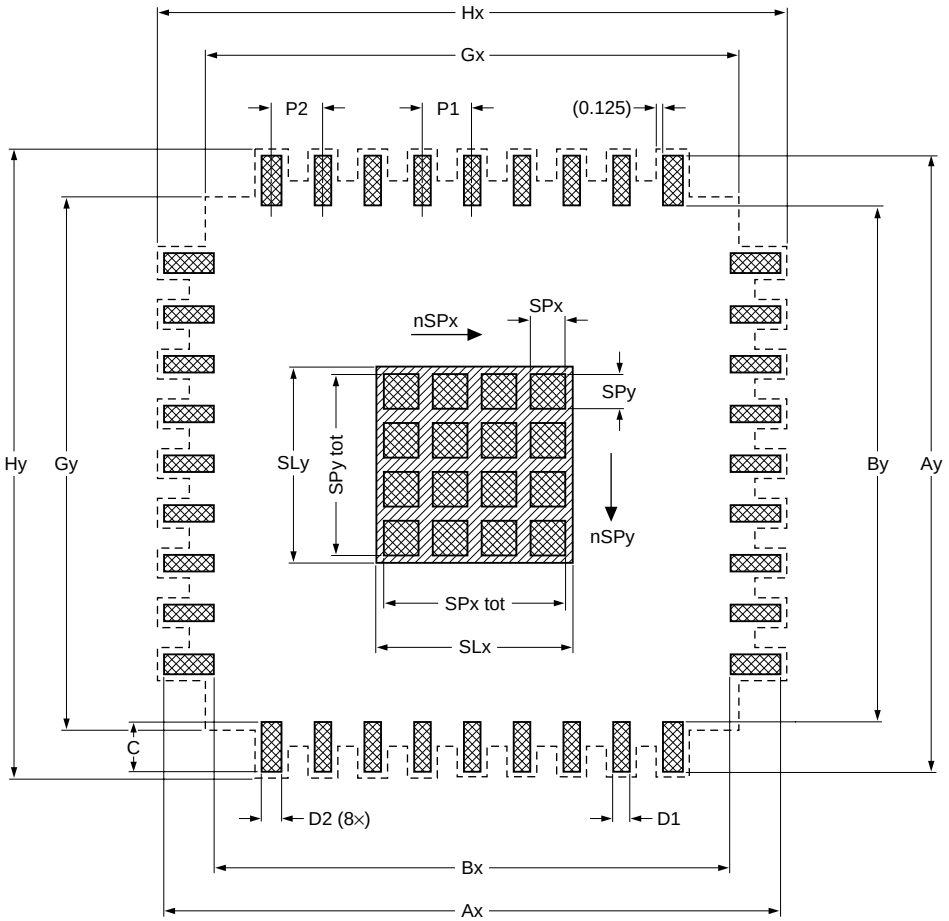
Footprint information for reflow soldering of HTQFP80 package **SOT841-4**



Generic footprint pattern

Refer to the package outline drawing for actual layout

solder land

solder paste

occupied area

nSPx	nSPy
4	4

DIMENSIONS in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy	SLx	SLy	SPx tot	SPy tot	SPx	SPy
0.500	0.560	15.300	15.300	12.300	12.300	1.500	0.280	0.400	12.500	12.500	15.550	15.500	5.000	5.000	4.900	4.900	0.850	0.850

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